



## STEVAL-TDR007V1

3 stages RF power amplifier demonstration board using:  
PD57002-E, PD57018-E, 2 x PD57060-E

### Features

- N-channel enhancement-mode lateral MOSFETs
- Excellent thermal stability
- Frequency: 1030 MHz
- Supply voltage: 36 V
- Peak power: 200 W typical
- Input power: 23 dBm
- Harmonics < -45 dBc
- Rise and fall time < 100 ns
- RoHS compliant

### Description

The STEVAL-TDR007V1 is a 200 W RF power amplifier intended for IFF - 1030 MHz interrogator using PD57002-E + PD57018-E + 2 x PD57060-E N-channel lateral MOS field-effect transistors.

AB-2x57060-1030 is designed in cooperation with ETSA in France.

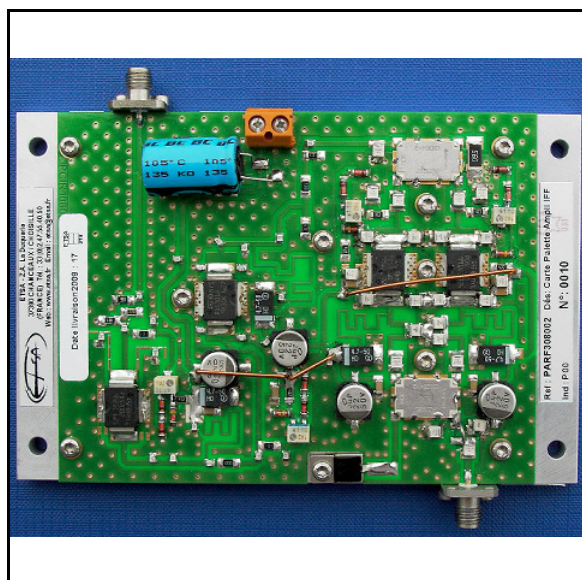


Table 1. Device summary

Order code
STEVAL-TDR007V1

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# 1 Electrical data

## 1.1 Maximum ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value	Unit
$V_{DD}$	Supply voltage	36	V
$I_D$	Drain current	1.0	A
$T_{CASE}$	Operating case temperature	+80	°C
$T_A$	Max. ambient temperature	-10 to +50	°C

# 2 Electrical characteristics

$T_A = +25\text{ °C}$ ,  $V_{DD} = 36\text{ V}$ ,  $I_{dq} = 100\text{ mA}$ , Freq. = 1030 MHz, PW = 32  $\mu\text{s}$ , DC = 2.5 %

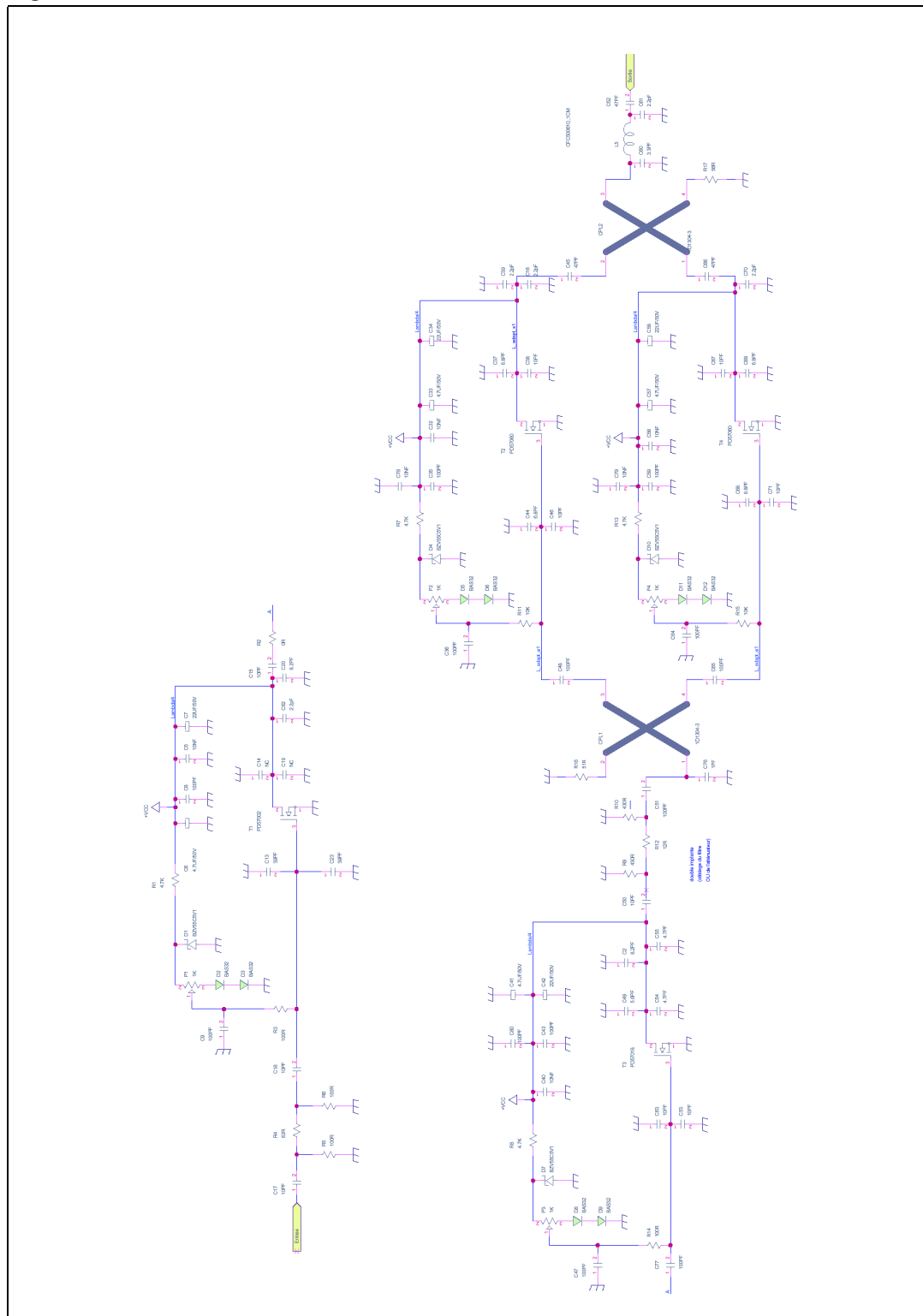
**Table 3. Electrical specification**

Symbol	Test conditions	Min	Typ	Max	Unit
$P_{OUT}$	@ $P_{IN} = 23\text{ dBm}$	52	53		dBm
IRL	@ $P_{IN} = 23\text{ dBm}$			-10	dB
$I_{TOTAL}$	@ $P_{IN} = 23\text{ dBm}$		500	600	mA
Rise and Fall time	@ $P_{IN} = 23\text{ dBm}$			100	ns
Power droop <sup>(1)</sup>	@ $P_{IN} = 23\text{ dBm}$		0.2	1	dB
Harmonics	@ $P_{IN} = 23\text{ dBm}$		-60	-45	dBc

1. 1000  $\mu\text{F}$  connected to 36 V supply pin

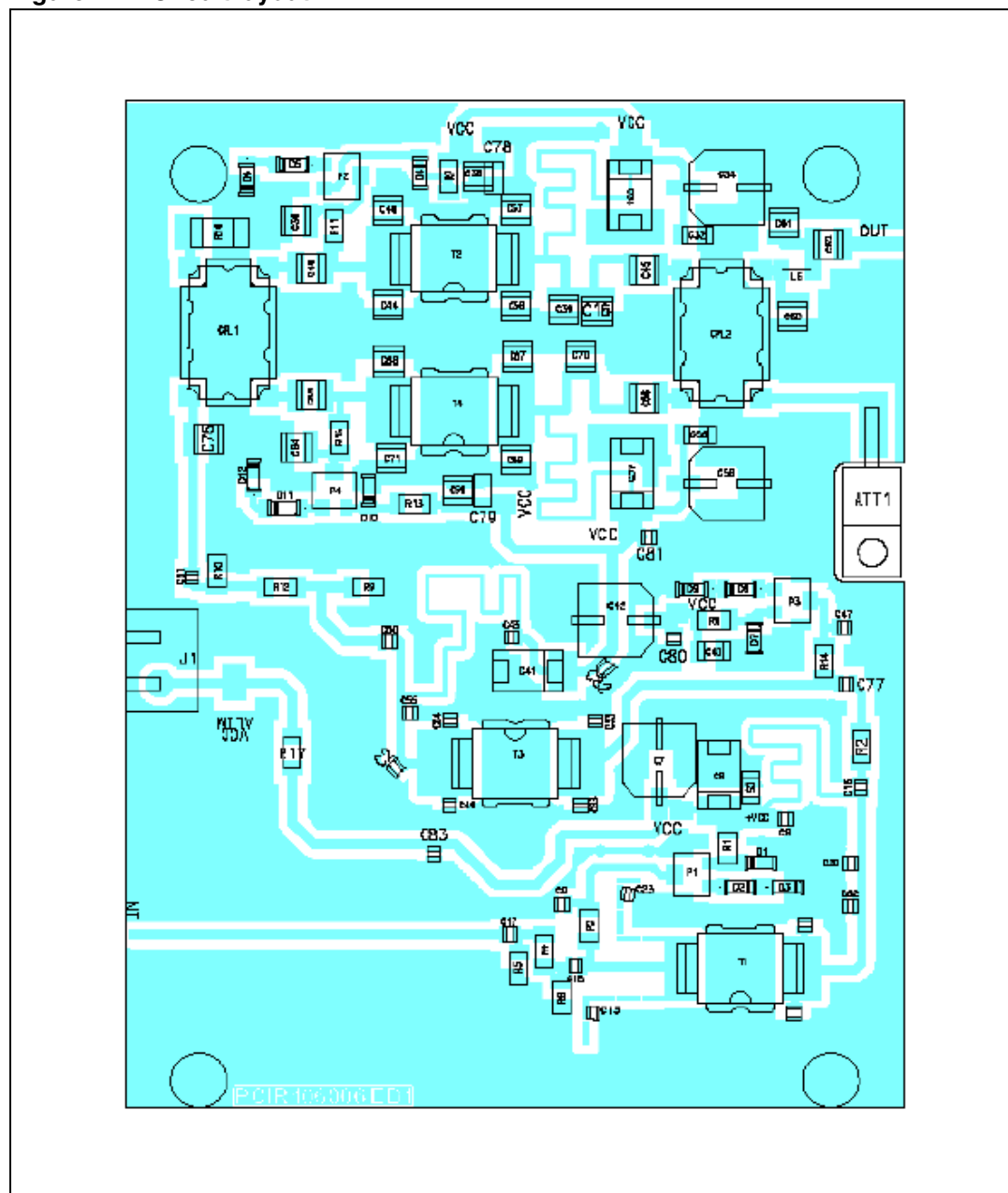
### 3 Circuit schematic

**Figure 1. Circuit schematic**



## 4 Circuit layout

Figure 2. Circuit layout



## 5 **Package mechanical data: PD57002-E, PD57018-E, PD57060-E**

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: [www.st.com](http://www.st.com)

## 5.1 Mounting indications

Figure 3. PowerSO-10 mounting indications

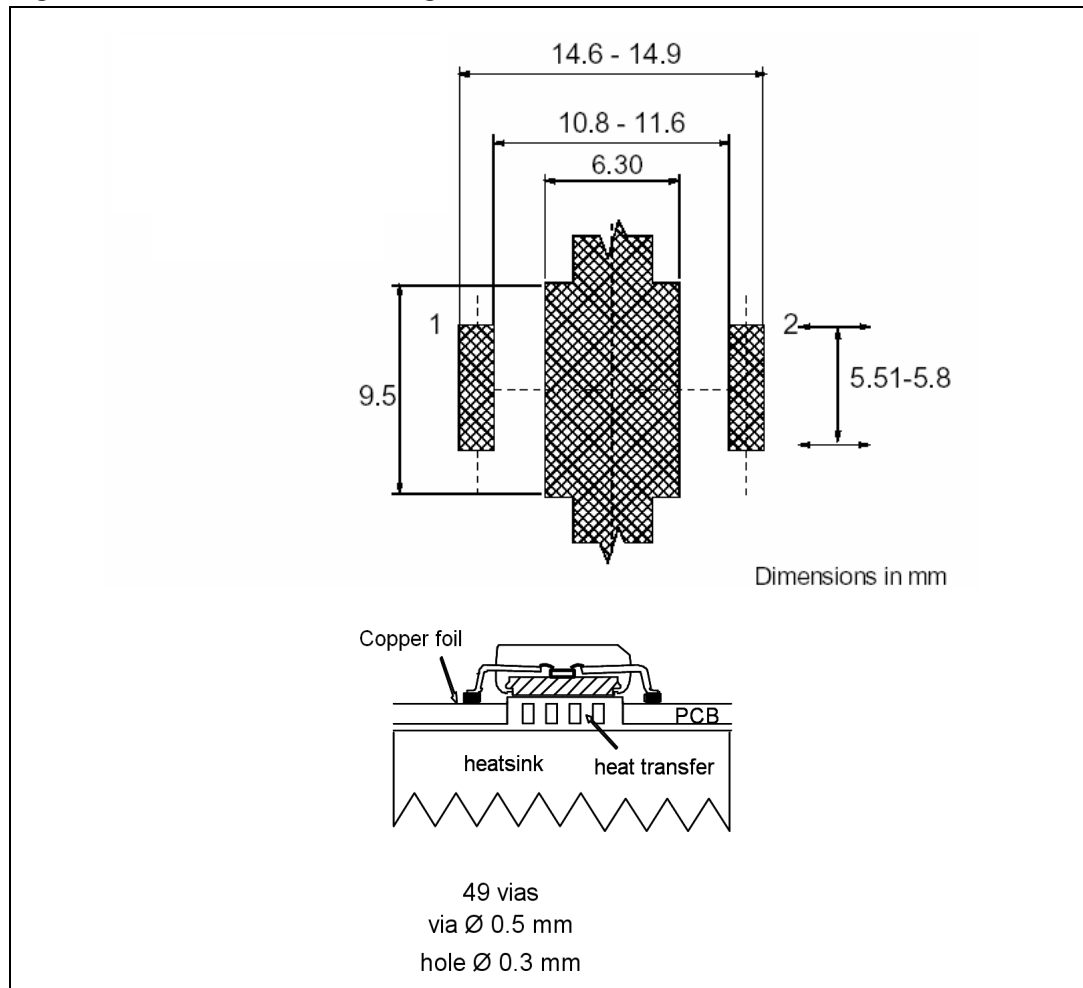
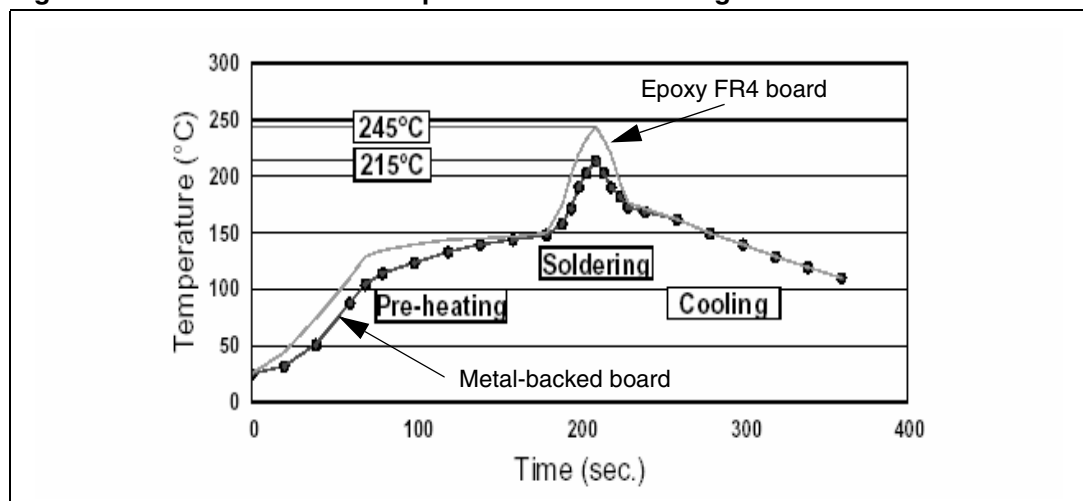


Figure 4. Recommended heat profile / reflow soldering



**Table 4. PowerSO-10RF formed lead (gull wing) mechanical data**

Dim.	mm.			Inch		
	Min	Typ	Max	Min	Typ	Max
A1	0	0.05	0.1	0.	0.0019	0.0038
A2	3.4	3.5	3.6	0.134	0.137	0.142
A3	1.2	1.3	1.4	0.046	0.05	0.054
A4	0.15	0.2	0.25	0.005	0.007	0.009
a		0.2			0.007	
b	5.4	5.53	5.65	0.212	0.217	0.221
c	0.23	0.27	0.32	0.008	0.01	0.012
D	9.4	9.5	9.6	0.370	0.374	0.377
D1	7.4	7.5	7.6	0.290	0.295	0.298
E	13.85	14.1	14.35	0.544	0.555	0.565
E1	9.3	9.4	9.5	0.365	0.37	0.375
E2	7.3	7.4	7.5	0.286	0.292	0.294
E3	5.9	6.1	6.3	0.231	0.24	0.247
F		0.5			0.019	
G		1.2			0.047	
L	0.8	1	1.1	0.030	0.039	0.042
R1			0.25			0.01
R2		0.8			0.031	
T	2 deg	5 deg	8 deg	2 deg	5 deg	8 deg
T1		6 deg			6 deg	
T2		10 deg			10 deg	

*Note:* Resin protrusions not included (max value: 0.15 mm per side)

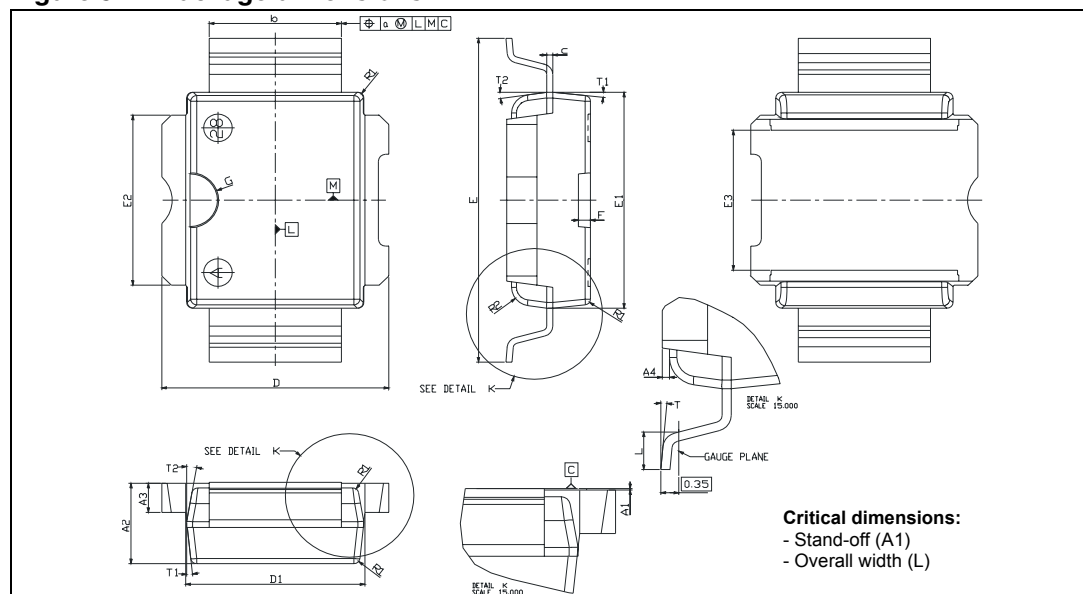
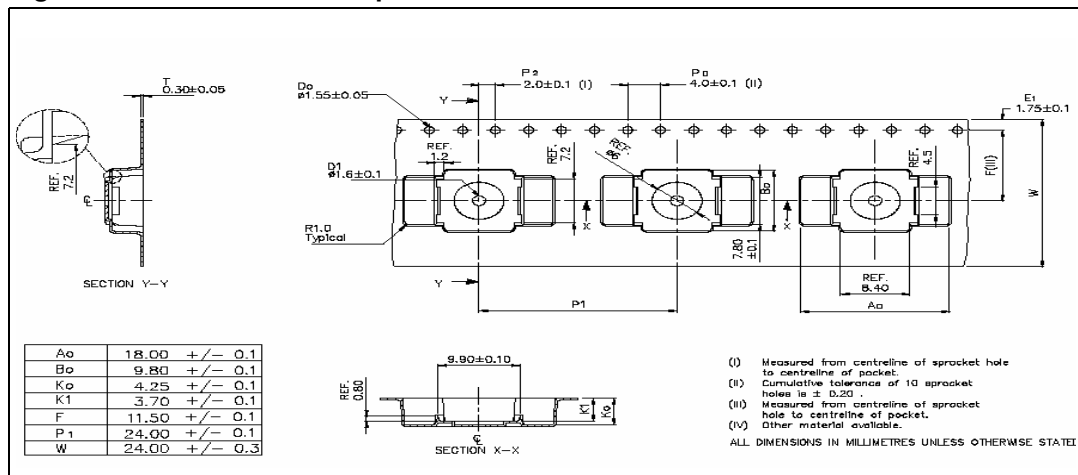
**Figure 5. Package dimensions**



Figure 6. PowerSO-10RF tape and reel



## 6 Revision history

**Table 5. Document revision history**

Date	Revision	Changes
01-Jul-2008	1	Initial release

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